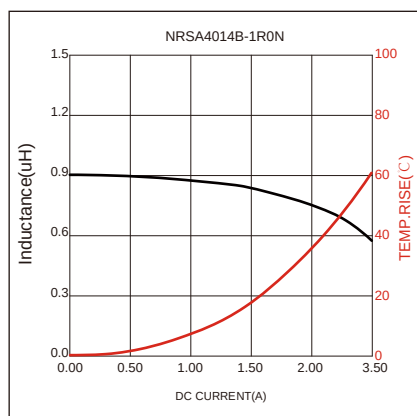
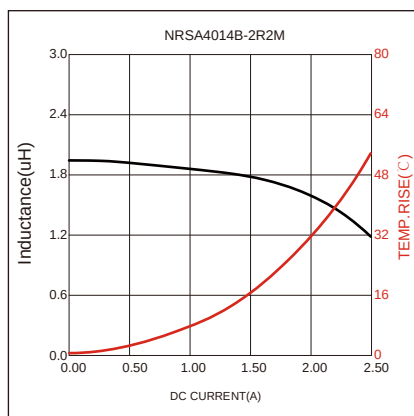
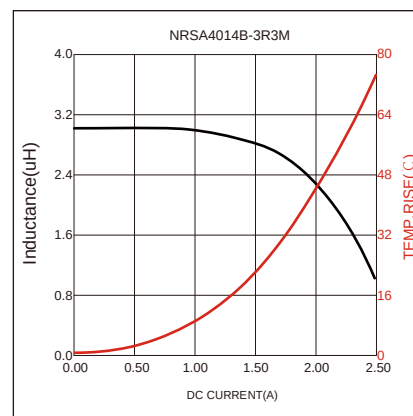
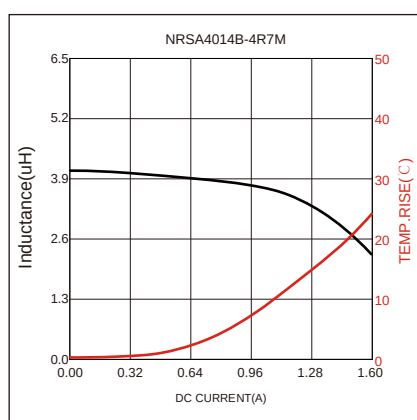


Typical Electrical Characteristics:

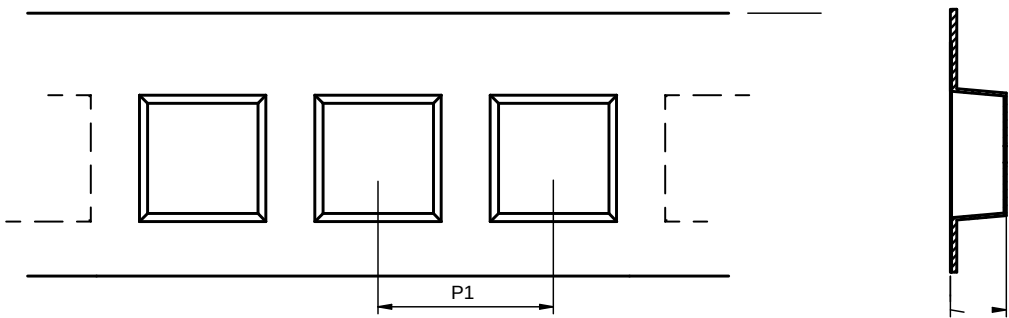


Soldering Reflow:

Preheat condition: 150 ~200℃ / 60~120 sec.
 Allowed time above 217℃ : 60~90 sec.
 Max temperature: 260℃ .
 Allowed Reflow time: 2x max.

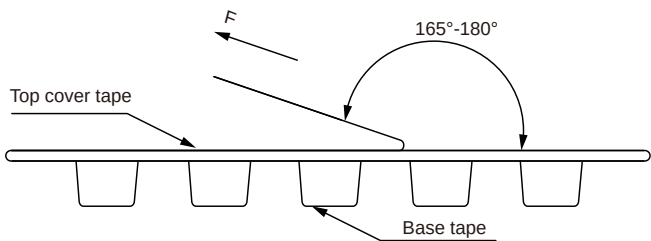
Packaging Information:

Tape Dimension :



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
LPQ?2./2@	2,03®./	2,03®./	/,3®./	2,./®./	6,./®./	/0,./®./,1	/,2®./	/,53®./	./,1.®./,3

Peel force of top cover tape:



Rfc nccj dmpac md rmn amtcp r_nc qf_jj `c `crucc l ./,1 rm /,/5 L

